



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



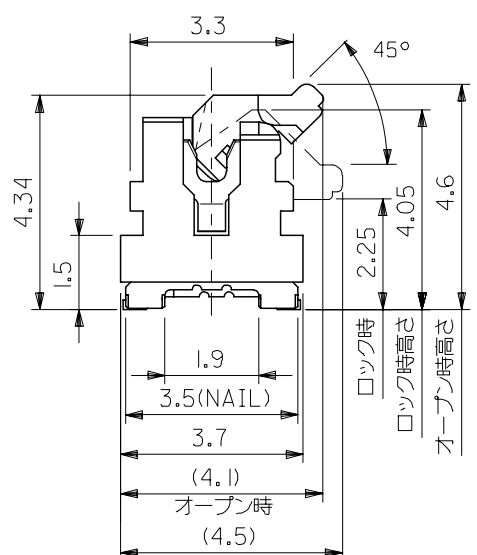
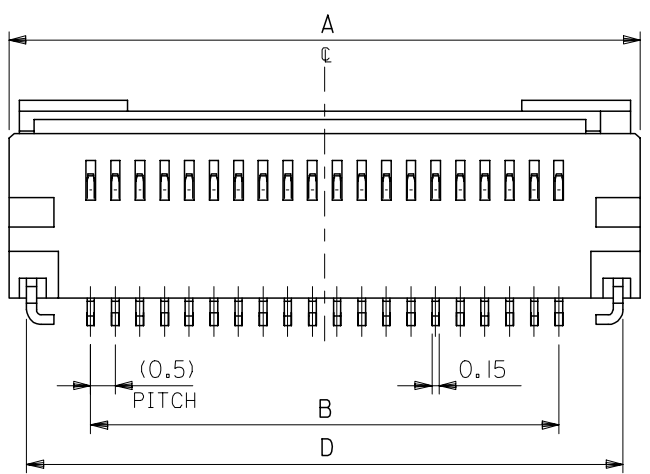
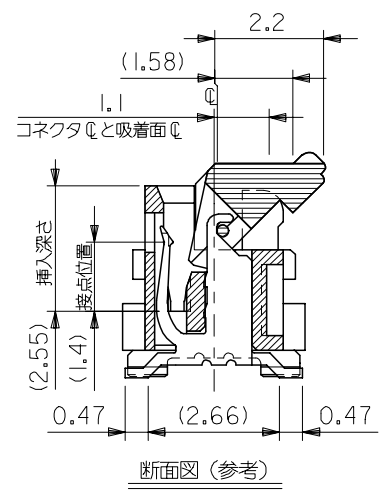
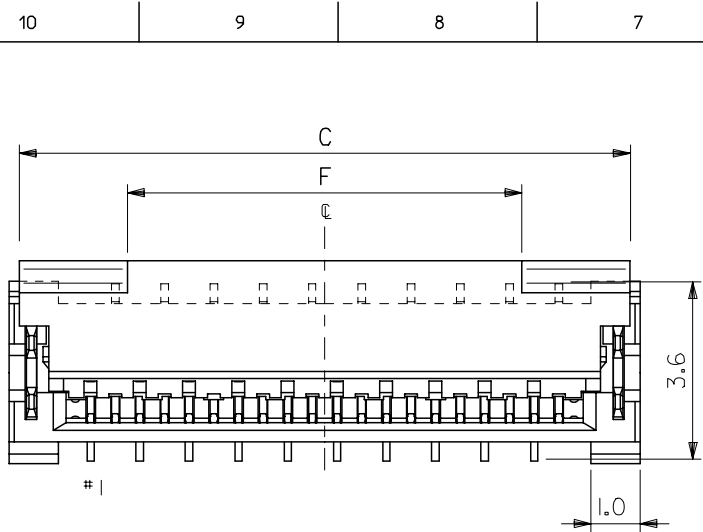
Contact us

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Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





注記
NOTES:

- 材質
MATERIAL
ハウジング: LCP (液晶ポリマー)、ガラス充填、白色、UL 94V-0
HOUSING: LCP (LIQUID CRYSTAL POLYMER), GLASS FILLED, WHITE, UL94V-0
アクチュエータ: PPS、ガラス充填、茶色、UL 94V-0
ACTUATOR: PPS (POLYPHENYLENE SULFIDE), GLASS FILLED, BROWN, UL94V-0
ターミナル: 銅合金 (t=0.15)
TERMINAL: COPPER ALLOY (t=0.15)
金具: 銅合金 (t=0.2)
NAIL: COPPER ALLOY (t=0.2)
- メッキ仕様
PLATING
ターミナル
TERMINAL
銅ヒスマスメッキ
TIN BISMUTH PLATING
下地メッキ: ニッケルメッキ
UNDER PLATING: NICKEL PLATING
金具
NAIL
銅メッキ
TIN PLATING
下地メッキ: ニッケルメッキ
UNDER PLATING: NICKEL PLATING
- テールと金具を併せた平坦度は、0.1ミリメートル以下。
TAILS AND NAILS COPLANARITY TO BE 0.1 MAXIMUM.
- 本製品は51374-***37/-***17の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 51374-***37/-***17.

8	30.7	32.1	32.4	29.5	32.8	51374-6039	60
	25.7	27.1	27.4	24.5	27.8	51374-5039	50
	23.2	24.6	24.9	22	25.3	51374-4539	45
	20.7	22.1	22.4	19.5	22.8	51374-4039	40
	17.2	18.6	18.9	16	19.3	51374-3339	33
	15.7	17.1	17.4	14.5	17.8	51374-3039	30
	13.7	15.1	15.4	12.5	15.8	51374-2639	26
	12.7	14.1	14.4	11.5	14.8	51374-2439	24
	10.7	12.1	12.4	9.5	12.8	51374-2039	20
	8.2	9.6	9.9	7	10.3	51374-1539	15
6	7.2	8.6	8.9	6	9.3	51374-1339	13
4.5	5.7	7.1	7.4	4.5	7.8	51374-1039	10
F	E	D	C	B	A	MATERIAL NO.	CIRCUITS

REVISED EC NO: J2005-0620 DRAWN: HSHIMOTA 2004/09/01 CHKD: HHIRATA 2004/09/01 APPR: HHIRATA 2004/09/06	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY M. NABE I	DATE 2004/02/18	TITLE 0.5 FPC CONN. HS'G ASS'Y EASY ON / STRAGIHT -LEAD FREE-	
	10 OVER 30 UNDER	±0.25	CHECKED BY M. SASAO	DATE 2004/02/18	MOLEX INCORPORATED	
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2004/02/18	DOCUMENT NO. SD-51374-020	SHEET NO. 1 OF 2
	ANGULAR	±1 °	MATERIAL NO. SEE TABLE			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

10 9 8 7 6 5 4 3 2 1

F

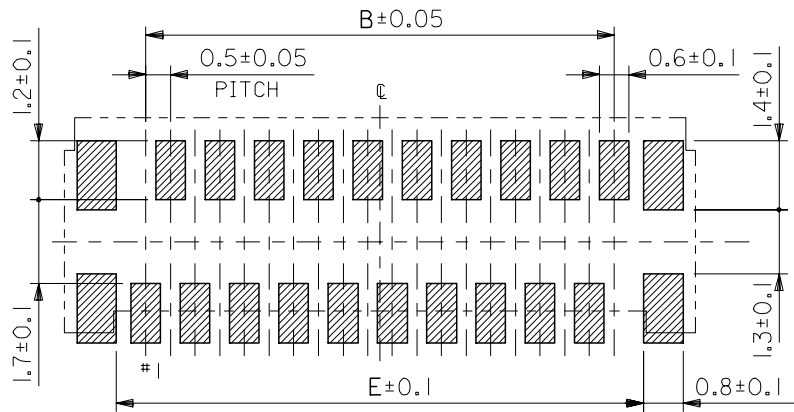
E

D

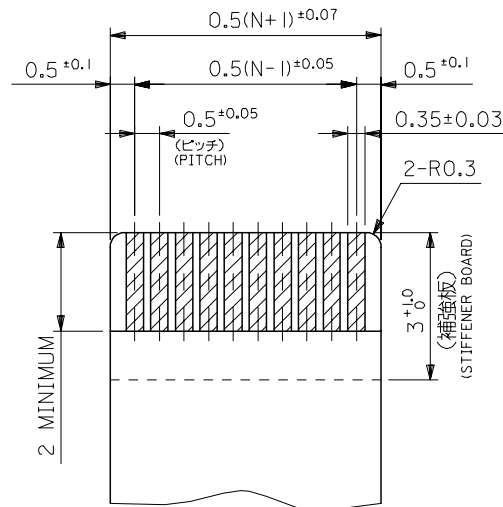
C

B

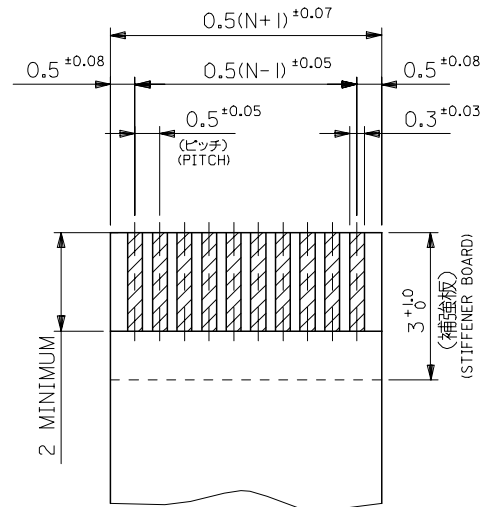
A



参考基板レイアウト (マウント面)
P.C. BOARD PATTERN DIMENSION (REF.)
(MOUNT AREA)



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)
N: 極数
N: CIRCUITS

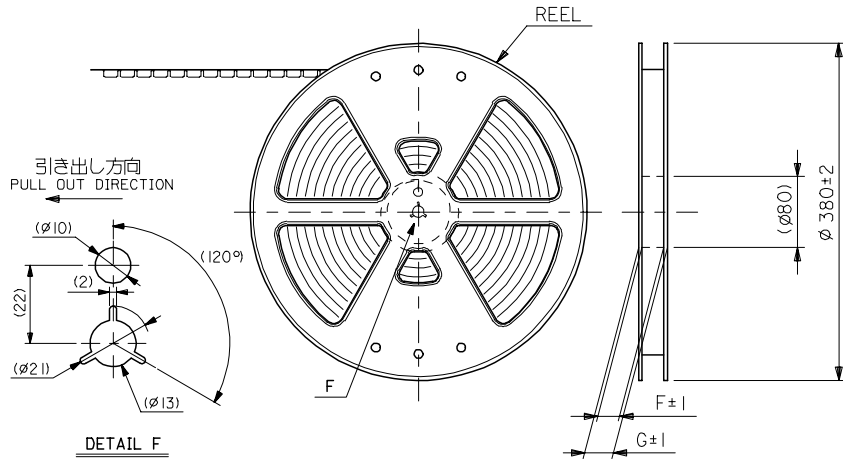


適合FFC推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)
N: 極数
N: CIRCUITS

FPCについて:
打抜き方向は導体側から補強板側を推奨致します。
補強フィルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

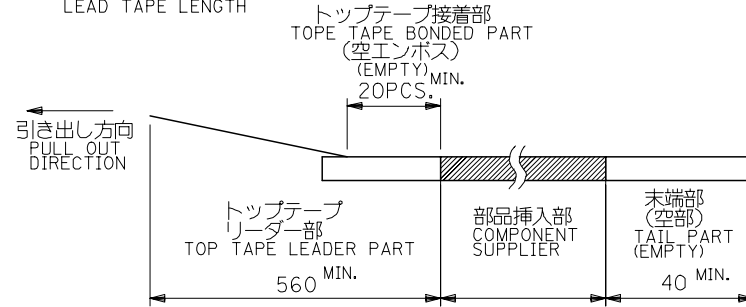
ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION: FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL: STIFFENER FILM: POLYIMIDE
BONDING AGENT: THERMOSETTING BONDING AGENT

REVISED EC NO: J2005-0620 DRAWN: HSHIMOYA 2004/09/01 CHKD: HHIRATA 2004/09/01 APPR: HHIRATA 2004/09/06 REV: B	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY M. NABEI	DATE 2004/02/18	TITLE 0.5 FPC CONN. HS'G ASS'Y EASY ON / STRAGIHT -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY M. SASAO	DATE 2004/02/18	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2004/02/18	DOCUMENT NO. SD-51374-020	SHEET NO. 2 OF 2	
	ANGULAR	±1 °	MATERIAL NO. SEE TABLE				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



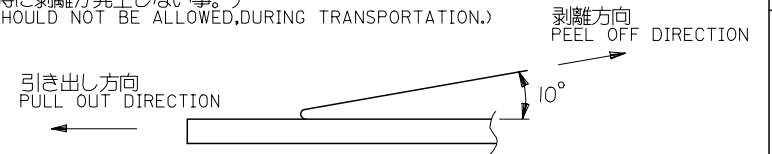
注)
NOTES

1. 製品番号 51374-**-39 詳細寸法については、製品単体図面を参照下さい。
IN THE PACKAGE PART NUMBER 51374-**-39 DETAILED DIMENSIONS, SEE SALES DRAWING FOR CONNECTOR.
2. 梱包数量：2000個/リール
NUMBER OF CONNECTORS:2000 PCS/REEL.
3. リードテープ長さ
LEAD TAPE LENGTH



4. トップテープの剥離強度：(剥離方向は下図参照)
PEELING OFF FORCE OF TOP TAPE (PELLING DIRECTION AS SHOWN IN FOLLOWING FIGURE.)
0.1~1.3N {10~130gf}

尚、本規格値は、出荷時に適用。
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
(但し、輸送時に剥離が発生しない事。)
(PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTATION.)



5. 材料
MATERIAL
キャリアテープ：ポリプロピレン (PP)
CARRIER TAPE: POLYPROPYLENE (PP)
トップテープ：PET, PE, PEF
TOP TAPE: PET, PE, PEF
リール：ポリスチレン
REEL: POLYSTYRENE

6. 本製品は51374-**-93/-**-90の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 51374-**-93/-**-90.

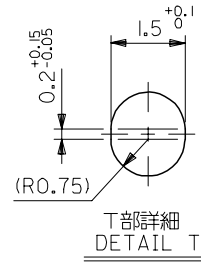
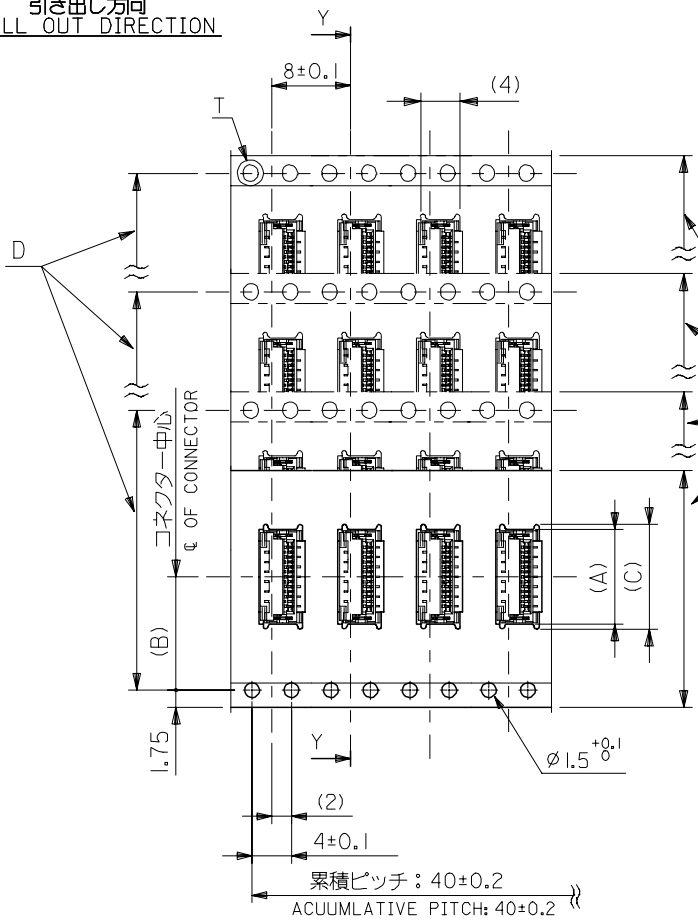
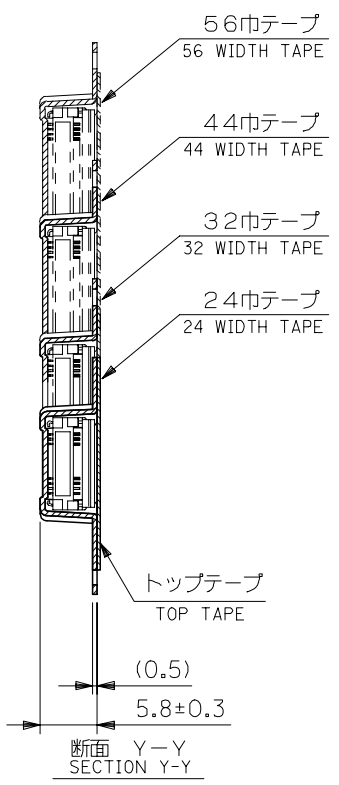
REVISED EC NO: J2005-0620 DRAWN: HSHIMOYA 2004/09/01 CHKD: HHIRATA 2004/09/01 APPR: HHIRATA 2004/09/06	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY M. NABEI	DATE 2004/02/18	TITLE 51374-**-39 TAPING PACKAGE -LEAD FREE-			
		10 OVER 30 UNDER	±0.25	CHECKED BY M. SASAO	DATE 2004/02/18	MOLEX MOLEX INCORPORATED			
		30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2004/02/18	DOCUMENT NO. SD-51374-021			
		ANGULAR	±1 °	MATERIAL NO. SEE TABLE		SHEET NO. 1 OF 2			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

10 9 8 7 6 5 4 3 2 1

F
E
D
C
B
A

F
E
D
C
B
A

引き出し方向
PULL OUT DIRECTION



61.4	57.4	56±0.3	52.4	34.1	26.2	33.1	51374-6073	60	
49.4	45.4	44±0.3	40.4	29.1	20.2	28.1	51374-5073	50	
				26.6		25.6	51374-4573	45	
				24.1		23.1	51374-4073	40	
37.4	33.4	32±0.3	28.4	19.1	14.2	18.1	51374-3073	30	
				17.1		16.1	51374-2673	26	
				16.1		15.1	51374-2473	24	
29.4	25.4	24±0.3	-	14.1	11.5	13.1	51374-2073	20	
				11.6		10.6	51374-1573	15	
				10.6		9.6	51374-1373	13	
				9.1		8.1	51374-1073	10	
G	F	E キャリアテープ幅 CARRIER TAPE WIDTH		D	(C)	(B)	(A)	製品番号 MATERIAL NO.	極数 CIRCUITS

REVISED EC NO: J2005-0620 DRAWN: HSHIMOYA 2004/09/01 CHKD: HHIRATA 2004/09/01 APPR: HHIRATA 2004/09/06	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
	10 UNDER	±0.2	DRAWN BY M. NABE I		DATE 2004/02/18		TITLE 51374-***39 TAPING PACKAGE -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY M. SASAO		DATE 2004/02/18		MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY M. SASAO		DATE 2004/02/18		DOCUMENT NO. SD-51374-021		
	ANGULAR	±1 °	MATERIAL NO.		SEE TABLE		SHEET NO. 2 OF 2		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					